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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10030435	FILING DATE 01/10/2002	CLASS 156	SUBCLASS 306.6	GAU 1733 1734	EXAMINER Goff
**APPLICANTS: Kariya Takashi;					
**CONTINUING DATA VERIFIED: THIS APPLICATION IS A 371 OF PCT/JP00/08105 11/16/2000					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 2000-137144 05/10/2000					
PG-PUB <input type="checkbox"/>		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO 217883US3PCT	
TITLE : Method of producing multilayer circuit boards					
U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)					

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NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	
		Print Claim for O.G.	
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Dwg.	Figs. Dwg.
		Print Fig.	
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner	
		Application Examiner	
		PREPARED FOR ISSUE	
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